

### **In the Specification**

Please amend the title as follows:

~~Semiconductor Constructions~~ And Methods Of Forming Semiconductor  
Constructions

At p. 1, before the "Technical Field" section, please insert:

### **RELATED PATENT DATA**

This patent resulted from a continuation application of U.S. Patent Application Serial  
No. 10/271,888, which was filed October 15, 2002 and which is a divisional of U.S. Patent  
Application Serial No. 09/592,604, which was filed June 12, 2000.